

# RoHS 2002/95/EC

# Vacuum Fluorescent Display Module Hardware Specification

Model: GU256X64F-A002

Specification No: DS-1359-0000-00

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This specification is subject to change without prior notice.

This product complies with RoHS Directive 2002/95/EC

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# 1 General Description

# 1.1 Scope

This specification covers the hardware and its requirements of the vacuum fluorescent graphic display module GU256X64F-A002.

#### 1.2 Construction

The module consists of a 256 x 64dot graphic BD-VFD, DC/DC converter, display controller, and all necessary control logic.

#### 1.3 Outline

Power supply:  $+ 5 V_{DC}$  only

Parallel interface: Supports the Intel 80xx type microprocessors (8-bit bus)

Supports the Motorola 68xx type microprocessors (8-bit bus)

Serial interface: Synchronous serial interface

Gray scale: 4 types available (2, 4, 8, 16 levels)

Display memory: 8K-byte on-chip SRAM

2 Gray scale mode : 4 screen 4 Gray scale mode : 2 screen 8 Gray scale mode : 1 screen 16 Gray scale mode : 1 screen

Function: Display control

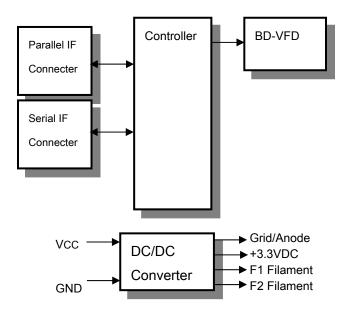
Layer Control Memory fill

For more detail;

Refer to specification:

DS-1359-0001-xx: "General function" spec.

#### 1.4 Block Diagram



# 2 Electrical specification

# 2.1 Absolute Maximum Ratings

#### **Power Supply Voltage**

Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Power Supply Voltage	VCC	-0.3	-	+6.0	VDC	

#### **Logic Supply Voltage**

Parameter		Symbol	Min.	Тур.	Max.	Unit	Note
Parallel IF	D0-D7, XWR/RW, XRD/EN, RS, XCS,	VpIN	-0.3	-	3.7	VDC	Note VCC=5.0V VCC=0V VCC=5.0V VCC=0V
i araller ii	XRD/EN, RS, XCS, XRESET	νριιν	-0.3		VCC+0.5	VDC	VCC=0V
Serial I/F	SPISI, SPICK,	\/alNl	-0.3	-	3.7	VDC	VCC=5.0V
Senai I/F	SPICS, ROMACS, XRESET	VsIN	-0.3	_	VCC+0.5	VDC	VCC=0V

VIN (VpIN & VsIN) are based on logic voltage (3.3V) made internally from VCC. So, Logic signal shouldn't be input in case of less than VCC=4.75V.

# 2.2 Electrical ratings

# Power Supply Voltage.

Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Power Supply Voltage	VCC	4.75	5.00	5.25	VDC	

All driving voltage for the VFD is converted from the DC/DC converter on board.

#### 2.3 Electrical Characteristics

#### Logic input/output condition

Measuring Conditions: Ambient temperature = 25degrees, VCC =5.0VDC

Parameter		Symbol	Min.	Тур.	Max.	Unit	Condition	Note
	Logic input current	lpIH1	-	-	1.0	uA	-	-
	D0-D7	lpIL1	-	-	-0.15	mA	-	-
	Logic input current XWR/RW, XRD/EN	VpIH2	-	-	1.0	uA	-	-
Parallel I/F	RS, XCS	VpIL2	-	-	-0.25	mA	-	-
i araller i/i	Logic input voltage	VpIH	2.0	-	-	VDC	-	-
	D0-D7, XWR/RW, XRD/EN, RS, XCS	VpIL	-	-	0.8	VDC	-	- - -
	Logic output voltage	VpOH	2.7	-	-	VDC	IpOH=-5mA	-
	WAIT	VpOL	-	-	0.5	VDC	IpOL=5mA	-
	Logic input current SPISI, SPICK, SPICS,	IsIH	-	-	1.0	uA	-	-
	ROMACS	IsIL	-	-	-0.15	mA	-	-
Serial I/F	Logic input voltage SPISI, SPICK, SPICS, ROMACS	VsIH	2.0	-	-	VDC	-	-
		VsIL	-	-	0.8	VDC	-	-
	Logic output voltage	VsOH	2.7	-	-	VDC	IsOH=-5mA	-
	SPISO	VsOL	-	-	0.5	VDC	IsOL=5mA	-
FRP	Logic output voltage	VfOH	2.7	-	-	VDC	IrOH=-5mA	
110	Logic output voltage	VfOL	-	-	0.5	VDC	IrOL=5mA	
	Logic input current	IrlH	-	-	1.0	uA		
XRESET	Logio input darront	IrIL	-	-	-0.65	uA		
, ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	Logic input voltage	VrIH	1.1	-	2.4	VDC		
		VrIL	0.5	-	1.7	VDC		
	Logic input current	ItIH	-	-	1.0	uA		
TEST		ItIL	-	-	-0.35	uA		
120.	Logic input voltage	VtIH	2.0	-	-	VDC	-	-
	gparage	VtIL	-	-	8.0	VDC	-	-

#### **Power Supply condition**

Measuring Conditions: Ambient temperature = 25degrees, VCC =5.0VDC

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition	Note
Power Supply Current 1	ICC1	-	1.4	1.8	ADC		(1)
Power Supply Current 2	ICC2	-	1.0	1.3	ADC		(2)
Power Supply Current 3	ICC3		20	30	mADC		(3)

#### Note

<sup>(1),(2)</sup> Icc1 shows the cuurent at all dots in the screen are lighted and Icc2 at all dots off. At power on rush, more than 2times current of above table should be expected. Provide the quick rise type power supply (<100msec.).

<sup>(3)</sup>Icc3 shows the current at Display Power OFF Mode (Display power control command).

# 3 Optical Specifications

Number of dots: 16,384 (256 x 64)

PCB Size:  $217.0 \text{mm} \times 64.0 \text{ mm} (X \times Y)$ Display area:  $162.41 \text{mm} \times 40.49 \text{mm} (X \times Y)$ Dot size:  $0.485 \text{mm} \times 0.485 \text{mm} (X \times Y)$ Dot pitch:  $0.635 \text{mm} \times 0.635 \text{mm} (X \times Y)$ Luminance:  $350 \text{cd/m}^2 \text{ Min.} (700 \text{cd/m}^2 \text{ Typ.})$ 

Color of illumination: Green (Blue Green)

#### 4 Environmental Specifications

Operating temperature: -40 to +70degreess Storage temperature: -40 to +85degrees

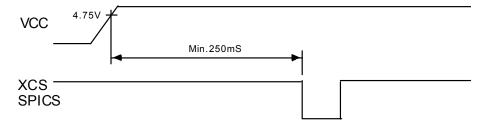
Storage humidity: 20 to 80 % R.H(Non Condensing)

Vibration: 10-55-10Hz, all amplitude 1mm, 30Min., X-Y-Z (Non operating)

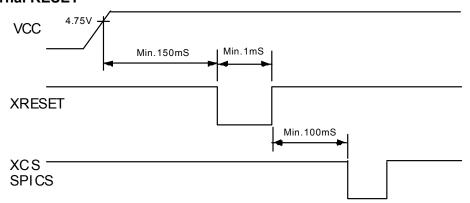
Shock: 392m/s<sup>2</sup> (40G) 9mS X-Y-Z (Non operating)

# 5 Reset Timing

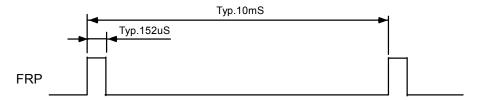
#### 5.1 At power ON



#### 5.2 External RESET



# 6 FRP Output Timing



\*This value is at normal operate condition(initial value).

# 7 Connector

# 7.1 Parallel Interface Connector (CN3)

Pin No.	Signal name	Function	Direction	Pin No.	Signal name	Function	Direction
1	D7	Data input	Bi-Direction	2	D6	Data input	Bi-Direction
3	D5	Data input	Bi-Direction	4	D4	Data input	Bi-Direction
5	D3	Data input	Bi-Direction	6	D2	Data input	Bi-Direction
7	D1	Data input	Bi-Direction	8	D0	Data input	Bi-Direction
9	GND	Ground	Input	10	XWR/RW	Data write	Input
11	GND	Ground	Input	12	XRD/EN	Data read	Input
13	GND	Ground	Input	14	RS	Command/Data	Input
15	GND	Ground	Input	16	XCS	Chip select	Input
17	GND	Ground	Input	18	WAIT*	Factory Use Only*	Output
19	FRP	Frame Pulse	Output	20	XRESET	Reset	Input

<sup>\*</sup> Internally connected. (Be sure to leave this pin open)

# 7.2 Serial Interface Connecter (CN2)

Pin No.	Signal name	Function	Direction
1	SPISO	Data Output	Output
2	SPISI	Data Input	Input
3	SPICK	Data Clock	Input
4	SPICS	Chip Select	Input
5	ROMACS *	Factory Use Only*	Input
6	FRP	Frame Pulse	Output
7	XRESET	Reset	Input
8	GND	Ground	Input

<sup>\*</sup> Internally connected. (Be sure to leave this pin open)

# 7.3 Power connector (CN1)

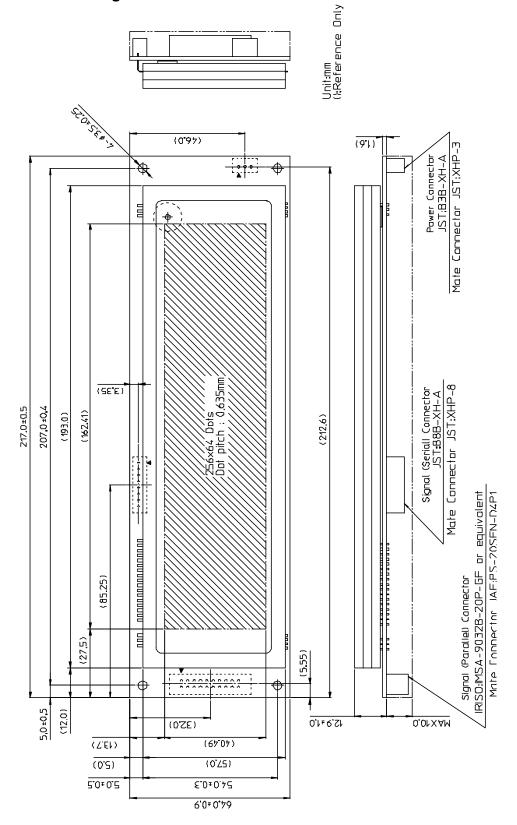
Pin No.	Signal name	Function	Direction
1	VCC	Power supply (5V)	Input
2	TEST*	Test (Factory use only)	Input
3	GND	Ground	Input

<sup>\*</sup> Internally connected. (Be sure to leave this pin open)

# 8 Other

Refer to "General Function Technical Data" for Detail of interface timing and Jumper setting.

# 9 Outline Drawing



# **Notice for the Cautious Handling VFD Modules**

#### Handling and Usage Precautions:

Please carefully follow the appropriate product application notes for proper usage, safety handling, and operation standards for maximum performance.

#### [VFD tubes are made of glass]

- Because the edges of the VFD glass-envelop are not smooth, it is necessary to handle carefully to avoid injuries to your hands
- Please avoid breaking the VFD glass-envelop to prevent injury from sharp glass particles.
- The tip of the exhaust pipe is fragile so avoid shock from impact.
- It is recommended to allow sufficient open space surrounding the exhaust pipe to avoid possible damage.
- Please design the PCB for the VFD-module within 0.3 mm warping tolerance to avoid any forces that may damage the display due to PCB distortion causing a breakdown of the electrical circuit leading to VFD failure.

#### [High voltage]

- Avoid touching conductive electrical parts, because the VFD-module uses high voltage exceeding 30∼100 volts.
- Even when electric power is turned off, it may take more than one minute for the electrical current to discharge.

#### [Cable connection]

- Do not unplug the power and/or data cables of VFD-modules during operating condition because unrecoverable damage may result.
- Sending input signals to the VFD-module during a power off condition sometimes causes I/O port damage.
- It is recommended to use a 30 cm or shorter signal cable to prevent functional failures.

#### [Electrostatic charge]

 VFD-modules need electrostatic free packaging and protection from electrostatic charges during handling and usage.

#### [Structure]

- During operation, VFD and VFD-modules generate heat. Please consider sufficient heat radiation dissipation using heat sink solutions.
- We prefer to use UL grade materials or components in conjunction with VFD-modules.
- Wrap and twist motion causes stress and may break VFDs & VFD modules. Please adhere to allowances within 0.3mm at the point of attachment.

#### [Power]

- Apply regulated power to the VFD-module within specified voltages to protect from failures.
- Because some VFD-modules may consume in rush current equal to twice the typical current at power-on timing, we recommend using a sufficient power capability and quick starting of the power regulator.
- VFD-module needs a specified voltage at the point of connection. Please use an adequate power cable to avoid a
  decrease in voltage. We also recommend inserting a power fuse for extra protection.

#### [Operating consideration]

- Illuminating phosphor will decrease in brightness during extended operation. If a fixed pattern illuminates for an extended period,( several hours), the phosphor efficiency will decrease compared to the non operating phosphor causing a non uniform brightness among pixels. Please consider programming the display patterns to use all phosphor segments evenly. Scrolling may be a consideration for a period of time to refresh the phosphor condition and improve even illumination to the pixels.
- We recommend using a signal cable 30cm or less to avoid some possible disturbances to the signal.

#### [Storage and operating environment]

• Please use VFD-modules under the recommended specified environmental conditions. Salty, sulfur and dusty environments may damage the VFD-module even during storage.

#### [Discard]

 Some VFDs contain a small amount of cadmium in the phosphor and lead in the solder. When discarding VFDs or VFD-modules, please adhere to governmental related laws or regulations.

#### [Others]

- Although the VFD-module is designed to be protected from electrical noise, please plan your circuitry to exclude as much noise as possible.
- Do not reconstruct or repair the VFD-module without our authorization. We cannot assure the quality or reliability of unauthorized reconstructed VFD-modules.

#### Notice:

- ·We do not authorize the use of any patents that may be inherent in these specifications.
- ·Neither whole nor partial copying of these specifications are permitted without our approval.

If necessary, please ask for assistance from our sales consultant.

•This product is not designed for military, aerospace, medical or other life-critical applications. If you choose to use this product for these applications, please ask us for prior consultation or we cannot take responsibility for problems that may occur.